ABSTRACT

SEMICONDUCTOR SYSTEM WITH FINE PITCH LEAD FINGERS

A semiconductor package system includes providing a die having a plurality of contact pads. A leadframe is formed having a plurality of lead fingers with the plurality of lead fingers having a fine pitch and each having a substantially trapezoidal cross-section. A plurality of bumps is formed on the plurality of lead fingers, the plurality of bumps are on the tops and extend down the sides of the plurality of lead fingers. A plurality of bond wires is attached to the plurality of contact pads and to the plurality of bumps. An encapsulant is formed over the plurality of lead fingers, the die, and the plurality of bond wires, the encapsulant leaving lower surfaces of the plurality of lead fingers exposed. (Fig. 1)